

2D/3D Laser Profiler

NEW LJ-X8000 Series

High-Resolution Inline Measurement 3200 points/profile



Measure Any Target with High Precision

KEYENCE

Designed to handle a wide-range of applications, from profile measurement to 3D inspection.





3D Inspection



High precision measurements performed inline

Capture the shape of targets in exceptional detail with the new standard in high-resolution measurement, 3200 points/profile.

Compatible with all materials

Capture stable profiles from any target, regardless of colour, material, or shape.

Set up in 3 easy steps

Measurement and inspection settings can be configured in three easy steps that any user can complete.



2D/3D Laser Profiler

Improved imaging capability makes it possible to measure or inspect any target with high precision.

Conventional measurement



Rough

PCB Inspection

Lower profile resolution limits the ability to accurately render the shape of a target.

Irregular

Noise such as light reflected from the target causes variations in measurement data and tracking errors.

Surface dependent

Image quality and measurement values can fluctuate based on the colour or gloss of a target.

Measurement with the LJ-X Series



Detailed

Each high resolution profile contains 3200 data points, so the shape of targets can be rendered in exceptional detail.

Consistent

Newly developed shape processing algorithms minimise the effect of noise and eliminate tracking errors.

Stable on any surface

By using an ultra-sensitive CMOS with wide dynamic range, the sensor can produce stable profiles on any target, including those with colour variation.

Select from a lineup designed to meet any application requirements

The LJ-X8000 series offers a wide range of sensors to support quality control and process improvement in any industry.



Choose a controller that fits your needs

With three different controller options available, you can find the perfect setup to match system capability with your inspection requirements and budget.

	2D/3D Controller LJ-X8000	2D Controller LJ-X8000E	Raw Data Output Controller LJ-X8000A
3D measurement mode	1		
2D measurement mode	1	1	
Profile output			1



2D/3D Controller LJ-X8000



2D Controller LJ-X8000E



Raw Data Output Controller LJ-X8000A



Ultra-high precision 3200 points/profile

Maximising resolution and target detection

To improve the resolution of the sensor, the number of pixels on the CMOS needs to be increased, which can be accomplished by making each pixel smaller. But smaller pixels can result in insufficient light to create an accurate profile of some target shapes or surfaces. For the LJ-X series, we've implemented new technology to create a laser profiler capable of high resolution measurement on any target.



High-quality components create high-resolution images

Cylindrical lens

Parallel light is emitted using a cylindrical lens designed to prevent the reflected light from scattering across the surface of the target. This ensures reliable reflections from any shape or surface.



Large-aperture receiver lens

In addition to the unique optical design, a large-aperture light-receiving lens that covers three times the area of the conventional lens is installed to deliver the increased amount of light received.



LJ-X Series

High-resolution CMOS

This newly developed CMOS enables high-resolution measurement using 3200 points/profile, while delivering improved imaging capability on targets with varying reflectivity.



2D measurement

Car door flush and gap

Control flush and gap at the micron level. By mounting the sensor on a multi-axial robot, inspections can be performed inline.

3D measurement

Brake rotor porosity

Using 3D images, it's possible to detect porosity in rough surfaces. High resolution profiles enable stable detection of even the smallest dents.



Accurately capture target shape

By creating each profile from 3200 data points, inspection can be performed using a profile that captures the shape of a target in more detail, improving measurement precision and defect detection.

Conventional System



Conventional systems have limited profile points which makes the shape rougher. Detecting small dents or protrusions was impossible.

LJ-X Series



With the LJ-X8000 Series, the shape of the target is accurately rendered using 3200 points/ profile. Abnormalities, such as small dents or protrusions, can be easily detected.

Ultra-high precision Improved precision in both the X-axis and Z-axis

Edge contour measurement

Bevels and other ultra-fine shapes can be accurately measured. Deliver higher quality to customers by inspecting 100% inline.



Comparison with conventional product

X-axis (width)

Improved X resolution produces higher precision width measurements.



Measurement precision (X-axis) 4x more resolution

Z-axis (height)

Improved Z-axis precision results in accurate height measurements.



Measurement precision (Z-axis) 3x more accurate

Tire shape / DOT code inspection

With improved X-axis and Z-axis precision, it's possible to holder tighter tolerances over a wider inspection area. This significantly expands the types of applications that can use 3D measurement.



Linearity comparison

X-axis direction

With 3200 points/profile, X-axis linearity has been significantly improved. Edge position can be tracked more reliably.



Z-axis direction

Z-axis linearity improvements make measurements of height difference and position more accurate.



Compatible with all targets Stable measurement on any material or surface

Smartphone assembly

Targets with multiple materials can be captured in a single profile, allowing measurements to be made between glass and metal surfaces. The LJ-X8000 series is equipped to handle reflectances ten times higher than conventional products.



Single-shot HDR

The profiler is equipped with an ultra-high-sensitivity CMOS featuring KEYENCE's single-shot HDR function. This provides the sensor with a dynamic range wide enough to reliably measure targets with multiple surface types (or areas of low reflectance and high reflectance) in a single shot.

Without single-shot HDR function

Low reflectance



When optimised for a flat area, the received light intensity of slopes or dark areas is insufficient



When optimised for sloped areas, the received light intensity of flat

areas is excessive

High reflectance

LJ-X Series



The shape of the target can be correctly rendered due to the high sensitivity and wide dynamic range

2D measurement

Coplanarity inspection

By eliminating the noise generated by differences in reflectivity and shape, it's possible to generate a stable profile for pin inspection.

3D measurement

Pulley shape measurement

By scanning the pulley as it spins, the sensor can detect chips and dents anywhere in the surface.



Newly developed Preserve Shape function

This is a filter that removes noise components caused by variations in reflected light, allowing the shape of the target to be maintained.







Deformation caused by smoothing

With preserve shape function

Newly developed

Irregular Reflection Removal function

The effects of stray light from glossy targets are suppressed, making it possible to render their shape accurately.



Stray light control OFF





Stray light control ON

Intuitive user interface reduces setup time 3-step configuration



Position detection	Tilt detection	Position correction	Configuration complete	
Creation & verification	Creation & verification	Creation & verification		
			.:	

Considerable time savings

STEP3

Position correction

Apply position correction to have inspection regions track with a feature's location.







Edge Position



Gravity Centre of Cluster



(Profile) Position



Line Position and Angle



Centre of Circle

Configuration complete

Start inspection

No external software required.



100% inspection made simple Get accurate results with 3D position tracking

3D position correction

Once the system is configured, the alignment and tilt of each part passing the sensor is calculated by comparing to a reference image. Each measurement tool will automatically latch on to the correct location, and eliminate any errors due to part misalignment.

11111-

Tilted

Tilted

Misalignment

Area profile measurement

Height inspection of PCB-mounted parts

Any variation in part presentation, such as angle or tilt, is automatically corrected to produce stable profile measurements.



If a PCB is misaligned or tilted, measurement and inspection cannot be performed correctly.

Area profile measurement detects target position shifts and tilt and automatically performs correction, enabling stable inspection.

2D profile measurement

Door panel flush and gap



Measure door panel flush and gap without touching the car. The sensor settings don't need to be adjusted for variations in body colour or size, making it easy to automate external appearance inspection.



Mask tracking function

In cases where stray light due to scattered reflections cannot be eliminated with filters, a mask can be applied. Masks can dynamically track part location, so even if the height or position of the desired mask area changes, measurement results will not be impacted by stray light.

Apply a mask to stray light





Mask tracking ON







PCB chip height



Inspect the height, position, and shape of a mounted part. By using parallel light, the sensor captures target shape accurately, right down to the fine details.



LED lighting function

The profiler is equipped with an LED right beside the laser transmitter.

This illuminates the area on the measurement target that is currently being captured by the laser, making it easy to understand where measurements are taking place.



Lighting setting OFF

Only the shape of the area being irradiated by the laser can be determined



Lighting setting ON It's possible to confirm where the laser line is located by viewing the target.



I 3D profile measurement

Inspection of mounted components



The height of mounted parts can be measured, using the surface of the PCB as a reference. The adjustment function can handle misaligned and tilted targets, so accurate inspection is possible without stopping the target.



Camera module assembly check



For camera modules with multiple functions, it's necessary to confirm the relative position of various elements. Performing high precision assembly inspection is possible with a single sensor using 3D data.



Sealant height, width, and volume



Improve quality control by confirming sealant bead height, width, and area, rather than checking for presence alone. Even sudden, small abnormalities are detected.



Character recognition on cast surfaces (OCR)



Characters machined on cast surfaces can be identified. Detection using height data allows for stable reading, even for characters on rough metal surfaces.



I 3D appearance inspection

Brake pad dent inspection



Height images provide reliable detection on patterned surfaces

Height images are created by scanning a target and using colour to represent height changes. Patterns or markings on the surface do not impact the height image, making it easy to detect indentations or other defects.





Grayscale image







Indentation detection results

Weld shape inspection



Catch small changes in continuous processes

Profile measurement can be continuously performed on captured 3D shapes. This allows pass/fail criteria to be applied to maximum and minimum values over an area or period of time, making it possible to catch small defects in continuous processes.

Weld perforation sample





Image processing analysis is performed

I 3D appearance inspection

Sheet thickness and width



Extraction of uneven surfaces from free-form curved shapes

Defect inspections are possible by extracting changes in height from free-form curved surface information. Stable detection is possible even with complex curved shapes.



Lumber grading



Stable detection for targets with height differences

Highly accurate measurements can be made even when measuring targets with height differences or where the distance from the target to the camera could vary. Because the part image is focused anywhere in the Z-axis range, stable measurements can be performed on parts with height variation.

I When capturing inclined targets with a height difference of 40 mm



Height 40 mm

Ordinary 2D camera

Out of focus



LJ-X Series



Image captured clearly

Customise inspections using raw data

Sheet width measurement & defect inspection



Maximise flexibility by creating custom programmes

With the raw data output controller, you can output profiles at high-speed (up to 16kHz) and process the data using custom software. A sample programme is available with a comprehensive list of commands for obtaining profile data, issuing triggers, changing various settings, and so on.

There is also a programme for saving files in bitmap and TIFF format. The following languages are available:



Connection / Result			0	peration result log						
Operations for the DL		Contraction of the local distance of the loc						9	0	ar.
216arde P	raibe	Getversion							bistory.	
	Controlle	r connection status								
EthernetOpen	10	State (IP address)	Received							
CommunicationC lose	• 1 22 41 50 • 0 0 0 0 0	NoConnection NoConnection NoConnection NoConnection NoConnection NoConnection	0 0 0 0 0	¢						
Communication comma	nd			Communication command (rea	ding profiles					
System control				Buller size setting *Match the	setting of the	controller with this a	plication			
RebootController	0	ReturnToPactorySetting	ControlLaser	⊛ ⊔-x		O PA O	LI-VB			
GetError		ClearError	TRO_DRROR_RESET	Measurement range (X avis)	FULL	Massurement r	andia (X mus)	FULL		
GetTriggerAndPulseC	iount	GetHeadTemperature	GetSerialNumber	Thinning (X axis)	OFF	Thirring (X as	0	OFF		
GetAttentionStatu				Luminance output	ON	Enning		OFF		
				Sampling period	ikHz	~		Buffer size to be se	cured	2
Pressurement compos		Gadlinger	Christian	- samping period aneco	conning sec	ing		23628 090	e per pros	1
11004		SCALDHEADTLE	SICOMMERCIA	Get measurement results						
ClearMemory				GetProfile	Get	BatchProfile				J
Functions related to m	odifying o	r reading settings		Get measurement results (Sim	ple array me	hod)				
SetSetting		GetSetting	InitializeSetting		GetBal	chSingleArray		Save A	s Image F	í.
ReflectSetting		RevolteTemporarySetting	CheckHemoryAccess	High-speed data communicati	on related fu	nctions				
ChangeActiveProg	an 👘	GetActiveProgram		Use Simple Array		Start the timer	500	-		
				SnitalusHighSpeedDataCom	minication	Count only the	number of rea	ceived profiles.		
				InitializerighSpeed(Simpl	etrray)	Save the results fi	•			
				PreStartHighSpeedDataCom	munication	Save destination				
				Start9/ghSpeedDataComm	unication	Index of the profi	e to save	0		
				StopHighSpeedDataComm	unication	Number of profile	to save	1		
				Englantich Sound Date Com	an electron		-		-	

360° surface inspection



Synchronised measurement of multiple units

By triggering the master controller, other controllers are triggered at the same time. Each sensor can output profile data and luminance data.



Integrating the LJ-X8000 series into your process





Dedicated encoder



LJ-X sensor head



Monitor

Capture

KEYENCE's dedicated encoders can be set to any number of pulses, making it easy to install an encoder that matches with the capture conditions.

Measure

Perform high precision 2D and 3D measurements inline. Get the system up and running quickly with 3-step configuration.

Control

Based on measurement results, parts can be sorted in real-time. Data can be fed back to control upstream and downstream processes with a variety of communication methods.



Record

Gain a better understanding of your process by storing image and measurement data locally or on your server.



System Configuration



Head lineup





Monitor







CA-MP120 monitor stand

OP-87262





RGB monitor cable **OP-66842** (3 m) **OP-87055** (10 m)



I Programmable encoder





(industrial grade) 16 GB **CA-SD16G** 4 GB **CA-SD4G** 1 GB **CA-SD1G** 512 MB **OP-87133**



Dedicated mouse OP-87506 Mouse stand OP-87601

*The mouse is included with the controller CA-U4

Controller

Mandal		LJ-X8000/LJ-X8000E ^{'6}						
Model		2D mode	3D mode					
Head input		U Compatible with LJ-X8000 Series heads and LJ-V7000 S	Up to 2 head units Compatible with LJ-X8000 Series heads and LJ-V7000 Series heads *When using 2 units, heads A and B are the same model.					
Sampling cycle (trigger interval)		Maximum speed of 1 kHz (1 ms) ^{*1}	When connecting the LJ-X8000 Series: maximum speed of 16 kHz (62.5 μs) ² When connecting the LJ-V7000 Series: maximum speed of 64 kHz (16 μs) ³ (Luminance output types for model designations ending with B have a maximum speed of 8 kHz (125 μs)) ⁴					
Number of regi	stered inspection settings	Up to 1000 (depending on SD card capacity and setting	contents) for each of SD cards 1 and 2. External switching is possible					
Master profile /	number of reference images	Maximum 200 per setting per head (depends on SD card capacity)	Maximum 400 per setting (depends on SD card capacity)					
Memory card		SD card slot × 2 • Supports OP-87133 (512 I *In the SD1 slot, CA-SD4G is equipped as stand	SD card slot × 2 • Supports OP-87133 (512 MB), CA-SD1G (1 GB), CA-SD4G (4 GB), CA-SD16G (16 GB) "In the SD1 slot, CA-SD4G is equipped as standard for 8000, and CA-SD16 is equipped as standard for 8000F					
Number of tool	s	100/setting (of those, 20 are for misalignment correction)	Maximum of 100/setting					
	Control input	20 points (input terminal	l block: 5 points, parallel I/O: 15 points)					
	Control output	28 points (output terminal block: 6	points, parallel I/O: 22 points) • Photo MOSFET ⁵					
	RS-232C	Value output and control I/O (exclusive use with PLC I	ink using an RS-232C port) • Supports baud rates up to 230,400 bps					
	PLC link	Value output using Ether (Exclusive use with EtherNet/IP™ and PROFINET. When using	net port or RS-232C port, and control I/O an RS-232C port, exclusive use with RS-232C no-procedure communication)					
	Ethernet	Value In addition to the above functions, can uploa send/receive various c and be used with remote connection Supports FTP - Supports VNC server functions (for non-P Supports BOOTP function	output and control I/O d/download inspection settings, perform various simulations, lata including profile and image data, programmes via KEYENCE PC application software client and FTP server functions C clients, only displaying the monitor screen is supported) s • 1000BASE-T/100BASE-TX/10BASE-T					
Interface	USB	Can output values (3D mode only), upload/download inspection settings, perform various simulations, send/receive various data including profile and image data, and be used with remote connection programmes via KEYENCE PC application software						
	EtherNet/IP™	 Value I/O and control I/O using Ethernet port (exclusive use with PLC link and PROFINET) Supports cyclic communication (max. 1436 bytes) and message communication Maximum Connections: 32 Conforms to Version.CT15 conformance test 						
	PROFINET	Value input and control input/output using Ethernet port (when this is in use, PLC-Link and EtherNet/IP™ cannot be used Supports cyclic communication (max. 1408 bytes) • Supports non-cyclic communication (record data) Conforms to Conformance Class A						
	Mouse	Various menus can be controlled via the dedicated mouse (included with the controller)						
	SNTP	Automatic correction of date and time for	r this unit is possible by connecting to an SNTP server					
	USB HDD	By connecting an HDD (max. 2 TB) to the dedicated USB port (supports USB 3.0, bus-powered, rated output: 900 mA), profile, image and other data can be output						
	Monitor output	Analogue RGB output,	XGA 1024 × 768 (24-bit colour, 60 Hz)					
Encoder input		1 port: combination RS-422 line-driver output (with 5 V output: maximum 150 mA) open collector output (compatible with 5 V. 12 V. 24 V)						
Response	RS-422	Single phase / Z phase: 1.6 MHz, 2 phase /	1x: 1.6 MHz, 2 phase / 2x: 3.2 MHz, 2 phase / 4x: 6.4 MHz					
frequency Open collector (OC)		Single phase / Z phase: 100 kHz, 2 phase / 1x: 100 kHz, 2 phase / 2x: 200 kHz, 2 phase / 4x: 400 kHz						
Laser ON input		Non-voltage input (Shorted with short pin when shipped from factorv)						
Cooling fan			Provided					
Minimum display unit		0.1 µm. 0.01° 0.00001 mm² 0.0001 mm² 0.0001 mm²						
Language	-	Switchable between English, Japanese, Sir	nplified Chinese, Traditional Chinese, Korean and German					
	Power voltage	5 • • • • • • • • • •	24 V DC ±10%					
Ratings	Maximum current consumption		3.3 A					
Environmental	Operating ambient temperature	0 to +45°C (DIN rail mount	ing) / 0 to +40°C (base surface mounting)					
resistance	Operating ambient humidity	35 to 85%	6 BH (no condensation)					
Weight		Approx 2500 g						

*1 For LJ-X8080 and LJ-X8200 connection, when binning (Z) is ON, or when the measurement range (Z) is set to 1/2. LJ-X8900 when the measurement range (Z) is set to 1/2. *2 When the measurement range is narrowed in accordance with the binning settings. *3 When the measurement range is set to minimum, binning is ON, and parallel imaging is ON. All other settings are default values.

*4 When binning and parallel imaging are both ON. All other settings are default values.
*5 Positive common connection is supported for NPN input devices, and negative common connection for PNP input devices.
*6 3D mode cannot be used with the LJ-X8000E.

Model		LJ-X8000A				
Head input		1 unit, compatible with LJ-X8000 Series heads and LJ-V7000 Series heads				
		When connecting the LJ-X8000 Series: maximum speed of 16 kHz (62.5 µs) ⁻¹				
Sampling cycle	(trigger interval)	When connecting the LJ-V7000 Series: maximum speed of 64 kHz (16 µs) ²				
		(Luminance output types for model designations ending with B have a maximum speed of 8 kHz (125 μs)) ³				
	Control input	Compatible with batch measurement start (MEASURE_START) and batch measurement stop (MEASURE_STOP)				
Interface	Control output	Compatible with trigger ready (READY) and system error (ERROR), Photo MOSFET ⁻⁴				
Interface	Synchronised I/O	nchronised I/O For multiple controller trigger synchronisation '5				
	Ethernet 6	Profile output, settings, control, 1000BASE-T/100BASE-TX				
Encoder input		1 port: combination RS-422 line-driver output (with 5 V output: maximum 150 mA) open collector output (compatible with 5 V, 24 V)				
Response	RS-422	Single phase / Z phase: 1.6 MHz, 2 phase / 1x: 1.6 MHz, 2 phase / 2x: 3.2 MHz, 2 phase / 4x: 6.4 MHz				
frequency	Open collector (OC)	Single phase / Z phase: 100 kHz, 2 phase / 1x: 100 kHz, 2 phase / 2x: 200 kHz, 2 phase / 4x: 400 kHz				
Laser ON input		Non-voltage input (Shorted with short pin when shipped from factory)				
Dotingo	Power voltage	24 V DC ±10%				
naungs	Maximum current consumption	1.3 A				
Environmental	Operating ambient temperature	0 to 45°C (DIN rail mounting) / 0 to 40°C (Horizontal)				
resistance	Operating ambient humidity	35 to 85% RH (no condensation)				
Weight		Approx. 700 g				

*1 When the measurement range is narrowed in accordance with the binning settings. *2 When the measurement range is set to minimum, binning is ON, and parallel imaging is ON. All other settings are default values. *3 When binning and parallel imaging are both ON. All other settings are default values. *4 Positive common connection is supported for NPN input devices, and negative common connection for PNP input devices.

*5 Exclusively for synchronised I/O between controllers (LJ-X8000A). *6 The PC application (LJ-H2X) includes communication libraries (DLL) and a sample programme. Types of communication libraries (DLL): Profile output, changing various settings, laser ON/OFF control, trigger input, etc.

Sensor head LJ-X Series

Moc	el		LJ-X8020	LJ-X8060	LJ-X8080	LJ-X8200	LJ-X8400	LJ-X8900	
Refe	erence distance		20 mm	64 mm	73 mm	245 mm	380 mm	980 mm	
Measur	Z-axis (height)	±2.2 mm (F.S.=4.4 mm)	±7.3 mm (F.S.=14.6 mm)	±20.5 mm (F.S.=41 mm)	±34 mm (F.S.=68 mm)	±60 mm (+95 to -220 mm ⁻¹¹) (F.S.=315 mm)	±400 mm (F.S.=800 mm)	
eme		NEAR side	7 mm	15 mm	30 mm	64 mm	180 mm(163 mm ^{*11})	300 mm	
nt ra	X-axis	Reference distance	7.5 mm	16 mm	35 mm	72 mm	210 mm	510 mm	
nge	(widin)	FAR side	8 mm	16 mm	39 mm	80 mm	240 mm(320 mm ^{•11})	720 mm	
		1			Blue s	emiconductor laser			
Ligh	Wavelength				405	nm (visible light)			
source	Laser class (IEC60825-1,	FDA (CDRH) Part 1040.10 ^{•1})			Class	2M laser product*9			
	Output					10 mW			
Spot size (reference distance)			Approx. 16 mm × 32 μm	Approx. 25 mm × 49 μm	Approx. 44 mm × 72 μm	Approx. 115 mm × 116 μm	Approx. 275 mm × 249 μm	Approx. 622 mm × 566 μm	
Dave		Z-axis (height) ^{*3}	0.3 µm	0.4 µm	0.5 µm	1 µm	5 µm	10 µm	
нер	eatability -	X-axis (width) ^{*4}	0.3 µm	0.5 µm	1.0 µm	3 µm	10 µm	25 µm	
Linearity		Z-axis (height)' ⁵	±0.05% of F.S. (±0.012%)	±0.04% of F.S. (±0.008%)	±0.03% of F.S. (±0.004%)	±0.04% of F.S. (±0.006%)	Reference distance: ±60 mm ±0.025% of F.S. (±0.003%) Total range: ±0.035% of F.S. (±0.005%)	Near~reference: distance ±0.015% of F.S. (±0.004%) Total range: ±0.05% of F.S. (±0.006%)	
Prof inter	le data val ^{*12}	X-axis (width)	2.5 μm (2 μm~)	5 μm (4 μm~)	12.5 μm (10 μm~)	25 μm (20 μm~)	75 μm (50 μm~) 100 μm (50 μm~) ^{*11}	225 μm (100 μm~)	
Prof	le data count		3200 points						
HDF	R (high dynamic	range)	Single-shot HDR ^{*10}						
Lase confi	r irradiation position rmation function	Light source	Blue LED (405 nm)						
Tem	perature charac	oteristic	0.01% of F.S./°C						
		Enclosure rating ⁶	IP67 (IEC60529)						
		Ambient operating illuminance ^{*7}			Incandescer	nt lamp: 10,000 lux o	or less		
Envi	ronmental	Ambient temperature ^{*8}				0 to +45°C			
resis	stance	Operating ambient humidity			20 to 85%	RH (no condensati	ion)		
		Vibration resistance		10 to 57 H	z, double amplitude	e 1.5 mm; 3 hours ea	ach for X, Y, and Z axes		
		Impact resistance				15 G / 6 msec			
Mate	erial					Aluminium			
Wei	ght		Approx. 1000 g	Approx. 1000 g	Approx. 1100 g	Approx. 1200 g	Approx. 1300 g	Approx. 1600 g	

*1 Classification performed based on IEC60825-1 in accordance with FDA (CDRH) Laser Notice No. 56. *2 Values measured by averaging 4096 times at the reference distance.

*3 The measured target is a KEYENCE standard target. Value when the average height of the default setting area is measured with height and position tools. All other settings are default values. *4 The measured target is a pin gauge. Value when the point of intersection for the pin gauge rounded surface and edge level is measured using height and position tools. All other settings are default values.

*5 The measured target is a KEYENCE standard target. Profile data when measured by smoothing 64 times and averaging 8 times. All other settings are default values. Values inside parentheses are representative examples of averages for all profile data.

To value when a head cable (CB-B) or extension cable (CB-B*) is connected. Does not include CB-B*L connection. *7 When measuring white paper, illuminance on the sensor head receiving surface when light is applied to white paper.

*8 The head needs to be mounted to a metal plate to be used.

*9 Do not view the beam directly using optical instruments (such as eye loupes, magnifiers, microscopes, telescopes, or binoculars).

Observing the laser output using optical instruments is dangerous and may damage the eyes. *10 A characteristic that allows for stable, high-precision measurement with a single capture (exposure) at all levels of reflectance, from black (low) to glossy surfaces (high).

*11 When range is extended.

*12 The profile data interval can be changed. If changed, the measurement range in the X direction will also change.

I LJ-H1X (LJ-X Series Simulation-Software/Terminal-Software) operating system environment

LJ-X Series Simulation-Software

Item	Required Environment
Supported OS	Microsoft Windows [®] 10 Home, Pro, Enterprise (supports 64-bit version only) Microsoft Windows [®] 7 Home Premium, Professional, Ultimate, Enterprise (supports 64-bit version only) • Japanese, English, and Chinese (simplified) are supported for the OS. • Cannot be used on an OS that is not listed.
CPU	Intel [®] Core [™] i3 processor equivalent or greater
Memory	8 GB or more
Free space on hard disk	8 GB or more (Separate space is required for storing image and profile data)
Display resolution	Minimum: 1024 × 768 pixels or larger, Recommended: 1280 × 1024 pixels or larger

LJ-X Series Terminal-Software

Item	Required Environment
Supported OS	Microsoft Windows [®] 10 Home, Pro, Enterprise Microsoft Windows [®] 7 Home Premium, Professional, Ultimate, Enterprise • Japanese, English, and Chinese (simplified) are supported for the OS. • Supports both 32-bit and 64-bit versions • Cannot be used on an OS that is not listed.
Running environment	CPU: Intel [®] Core [™] i3 processor equivalent or greater Memory: 2 GB or more HDD: 500 MB free space or more *Separate space is required for storing image and profile data Display resolution: 1024 × 768 pixels or larger (Recommended: 1280 × 1024 pixels or larger)

Sensor head LJ-X Series

LJ-X8020



LJ-X8020 in specular reflection

configuration

4 × M4 Effective depth: 2.8

> 3 × ø4.4 Mounting hole

(87)-

Π

*The value inside parentheses is a reference value calculated by tilting the dimensions during installation by 22.5 degrees. With CB-B05LU (L-shaped cable) connected





LJ-X8060 in specular reflection configuration





*The value inside parentheses is a reference value calculated by tilting the dimensions during installation by 17.5 degrees.







247.4 (Effective di 6.5 (Effectiv display 49.5 360 4-M4 Effective depth: 10 55.5 75 75

12" LCD colour monitor

CA-MP120





Mounting brackets Mounting screws

Controller

LJ-X8000





LJ-X8000A



Encoder relay unit

CB-B3/CB-B10

Head-to-controller cable



Head connection extension cable CB-B5E/CB-B10E/CB-B20E



I Head connection extension cable (L-shaped connector)

CB-B05LU/CB-B05LL/CB-B05LR



Dedicated encoder

CA-EN100H



35

High-speed profile measurement 64,000 profiles/second

High-speed 2D Laser Profiler

With the ability to capture profiles at 64,000Hz, the shape of targets being transported at high speeds by conveyor lines or devices can be measured without missing any data.





REVENCE

60.000 mm

135°

High-speed sampling allows detailed appearance data to be obtained

GP64-Processor

The sensor is equipped with a custom IC that enables a range of ultra-high-speed pipeline processing, from capture data reading to sub-pixel processing, linearisation processing, and data output. Perform measurements of targets moving at high speed.



High-speed measurement supports shorter takt times



The sensor is equipped with an HSE³-CMOS, which has both high sensitivity and a wide dynamic range. This enables stable measurements, even at high speeds.



Sensor head LJ-V Series

Model		LJ-V7020K ⁻¹ / LJ-V7020KB ⁻¹	LJ-V7020 ⁻¹ / LJ-V7020B ⁻¹	LJ-V7060K/ LJ-V7060KB	LJ-V7060/ LJ-V7060B	LJ-V7080/ LJ-V7080B	LJ-V7200/ LJ-V7200B	LJ-V7300/ LJ-V7300B	
Mou	nting condi	tions	Specular reflection	Diffuse reflection	Specular reflection	Diffuse reflection			
Reference distance		24.2 mm	20 mm	54.6 mm	60 mm	80 mm	200 mm	300 mm	
Measurement ra	Z-axis (height)		±2.3 mm (F.S. = 4.6 mm)	±2.6 mm (F.S. = 5.2 mm)	±7.6 mm (F.S. = 15.2 mm)	±8 mm (F.S. = 16 mm)	±23 mm (F.S. = 46 mm)	±48 mm (F.S. = 96 mm)	±145 mm (F.S. = 290 mm)
		NEAR side	6.5 mm	6.5 mm	8 mm	13.5 mm	25 mm	51 mm	110 mm
	X-axis (width)	Reference distance	7 mm	7 mm	14 mm	15 mm	32 mm	62 mm	180 mm
nge	. ,	FAR side	7.5 mm	7.5 mm	8 mm	15 mm	39 mm	73 mm	240 mm
					Blu	ue semiconductor las	ser		
Ę	Waveleng	th				405 nm (visible light))		
ght source	Laser class (IEC60825-1, FDA (CDRH) Part 1040.10 ^{°2})		Class	s 2M ^{*3}	Class 2	Class 2M ³	M ^{°3} Class 2		
	Output		10 r	nW	4.8 mW	10 mW		4.8 mW	
Spot size (reference distance)		Approx. 14 mm × 35 µm		Approx. 21 mm × 45 µm		Approx. 48 mm × 48 μm	Approx. 90 mm × 85 μm	Approx. 240 mm × 610 μm	
Z-axis		Z-axis (height) ^{*5}	0.3 µm		0.4	μm	0.5 µm	1 µm	5 µm
кер	eatability	X-axis (width) ^{*6}	2.5 μm		5 μ	ım	10 µm	20 µm	60 µm
Line	arity	Z-axis (height) ^{*7}	±0.1% of F.S.					From ±0.05% ±0.15% of F.S. ^{*8}	
Profi inter	le data val	X-axis (width)	10 µm		20 µm		50 µm	100 µm	300 µm
Profi	le data cou	int	800 points						
HDF	R (high dyna	amic range)	Single-shot HDR ^{*12}						
Tem	perature ch	naracteristic	0.01% of F.S./°C						
		Enclosure rating ^{*9}	IP67 (IEC60529)						
		Ambient operating illuminance ¹⁰			Incandes	cent lamp: 10,000 lu	ux or less		
Envi	ronmental	Ambient temperature ^{*11}				0 to +45°C			
resis	stance	Operating ambient humidity			20 to 8	85% RH (no condens	sation)		
		Vibration resistance	10 to 57 Hz, double amplitude 1.5 mm; 3 hours each for X, Y, and Z axes						
		Impact resistance	15 G / 6 msec						
Mate	erial					Aluminium			
Weight			Approx	. 410 g	Approx	. 450 g	Approx. 400 g	Approx. 550 g	Approx. 1000 g

*1 Double polarisation function cannot be used.

*2 Classification performed based on IEC60825-1 in accordance with FDA (CDRH) Laser Notice No. 50. *3 Do not view the beam directly using optical instruments (such as eye loupes, magnifiers, microscopes, telescopes, or binoculars).

Observing the laser output using optical instruments is dangerous and may damage the eyes. *4 Values measured by averaging 4096 times at the reference distance.

*5 The measured target is a KEYENCE standard target. Value when the average height of the default setting area is measured with height and position tools. All other settings are default values.

*6 The measured target is a pin gauge. Value when the point of intersection for the pin gauge rounded surface and edge level is measured using height and position tools. All other settings are default values.
*7 The measured target is a KEYENCE standard target. Profile data when measured by smoothing 64 times and averaging 8 times. All other settings are default values.

*8 Linearity will vary depending on the measuring area (refer to the figure on the right) *9 The value when a head cable (CB-B*) or extension cable (CB-B*E) is connected.

*10 When measuring white paper, illuminance on the sensor head receiving surface when light is applied to white paper. *11 The head needs to be mounted to a metal plate to be used.

*12 A characteristic that allows for stable, high-precision measurement with a single capture (exposure) at all levels of reflectance, from black (low) to glossy surfaces (high).

• Model designations ending with B are luminance output types. The multi emission (optimising light) and multi emission (synthesis) imaging modes are not available.



Sensor head LJ-V Series

LJ-V7020K/LJ-V7020KB



LJ-V7060K/LJ-V7060KB

LJ-V7060/LJ-V7060B

19

(85) -3 × ø4.4 Mounting

][_):=:

21

LJ-V7080/LJ-V7080B







LJ-V7200/LJ-V7200B



LJ-V7300/LJ-V7300B







KEYENCE

Please visit: WWW.keyence.com



SAFETY INFORMATION

lease read the instruction manual carefully in rder to safely operate any KEYENCE product.

GLOBAL NETWORK

CHINA Phone: +86-21-5058-6228

BRAZIL

CZECH REPUBLIC Phone: +420 220 184 700 AUSTRIA Phone: +43 2236 378266 0 BELGIUM Phone: +32 15 281 222 Phone: +55-11-3045-4011 CANADA Phone: +1-905-366-7655

FRANCE Phone: +33-1-56-37-78-00 GERMANY Phone: +49-6102-3689-0 HONG KONG Phone: +852-3104-1010 HUNGARY Phone: +36 1 802 73 60

INDIA Phone: +91-44-4963-0900 INDONESIA Phone: +62-21-2966-0120 ITALY Phone: +39-02-6688220 JAPAN Phone: +81-6-6379-2211 KOREA Phone: +82-31-789-4300

MALAYSIA Phone: +60-3-7883-2211 MEXICO Phone: +52-55-8850-0100 NETHERLANDS Phone: +31 40 20 66 100

PHILIPPINES Phone: +63-2-8981-5000

POLAND Phone: +48 71 36861 60 ROMANIA Phone: +40 269 232 808 SINGAPORE Phone: +65-6392-1011

SLOVAKIA Phone: +421 2 5939 6461

SLOVENIA Phone: +386 1 4701 666

SWITZERLAND Phone: +41 43 455 77 30 TAIWAN Phone: +886-2-2721-8080

THAILAND Phone: +66-2-369-2777

UK & IRELAND Phone: +44 1908-696-900

USA Phone: +1-201-930-0100

VIETNAM

Phone: +84-24-3772-5555

WW1-1109

The information in this publication is based on KEYENCE's internal research/evaluation at the time of release and is subject to change without notice. Company and product names mentioned in this catalogue are either trademarks or registered trademarks of their respective companies. Unauthorised reproduction of this catalogue is strictly prohibited. Copyright © 2019 KEYENCE CORPORATION. All rights reserved.

CONTACT YOUR NEAREST OFFICE FOR RELEASE STATUS

LJ-X8000Catlog-WW-C2-GB 2020-6 600V39